Product End-of-Life Disassembly Instructions

Marketing Name/Model	**Description**
HP Carrier-Grade Server cc3310	Dual Xeon™, NEBS Compliant, 2U Rack Mount Server

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of this product to remove components and materials requiring selective treatment.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

HP Carrier-Grade Server cc3310		
Item Description	**Notes**	**Quantity of items included in product.**
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 square cm	4
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 square cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB / PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

2.1 List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	**Tool Size**
Philips Screw Driver	#2
Flat Head Screw Driver	Small
Flat Head Screw Driver	Large

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1	Battery – locate battery and remove by hand or small flat blade screw driver.
2	Capacitor – locate capacitor and pry from the PCB with a large flat head screw driver.
3	PCB’s – follow removal instructions found in the system specific documentation if needed.